



## PRODUCT SPECIFICATION

# 8266M-PU

Wi-Fi Tri-band 2T2R 11ax +Bluetooth 5.3

PCIe Combo Module

Version:v1.0

Customer: \_\_\_\_\_

Customer P/N: \_\_\_\_\_

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

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## 8266M-PU Module Datasheet

Ordering Information	Part NO.	Description
	FG8266MPUX-00	QCA-2066-5,WiFi6E,DBS 802.11a/b/g/n/ac/ax +BT5.3,2T2R, ,PCIe/USB,22*30mm M.2 interface

Target power

2.4G:17/14/13/10

5G: 13/12/10/9

6G: 12/10/9/7

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# 1. General Description

## 1.1 Introduction

8266M-PU is a highly integrated single module supporting 2x2 multi-user MIMO 802.11ax Wi-Fi and Bluetooth (BT) Milan.that with WLAN PCI Express network interface controller and USB interface. supporting simultaneous operation on 2.4 GHz and 5 GHz/ 6 GHz, also known as Dual Band Simultaneous(DBS). DBS mode provide up to 3 Gbps data rate(2x2+2x2 11ax DBS).

## 1.2 Description

Model Name	8266M-PU
Product Description	Support Wi-Fi/Bluetooth functionalities
Dimension	L x W x H: 22x 30x 2.2 (typical) mm
Wi-Fi Interface	Support PCIe
BT Interface	USB
OS supported	Android /Linux/ Win CE /iOS /XP/WIN7/WIN10
Operating temperature	-20°C to 70°C
Storage temperature	-40°C to 85°C

## 2. Features

### General Features

- Support IEEE802.11a/b/g/n/ac/ax .
- Supports 2x2 Multi-User Multiple-Input Multiple-Output (MU-MIMO).
- Dual Band Simultaneous (DBS), up to 3 Gbps data rate (2x2+2x2 11ax DBS) .
- Support Tri-band 2.4 GHz/5 GHz/6 GHz.
- 20 MHz/40 MHz channel bandwidth for 2.4 GHz and 20MHz/40 MHz/80 MHz/160 MHz channel bandwidth for 5GHz/6 GHz.

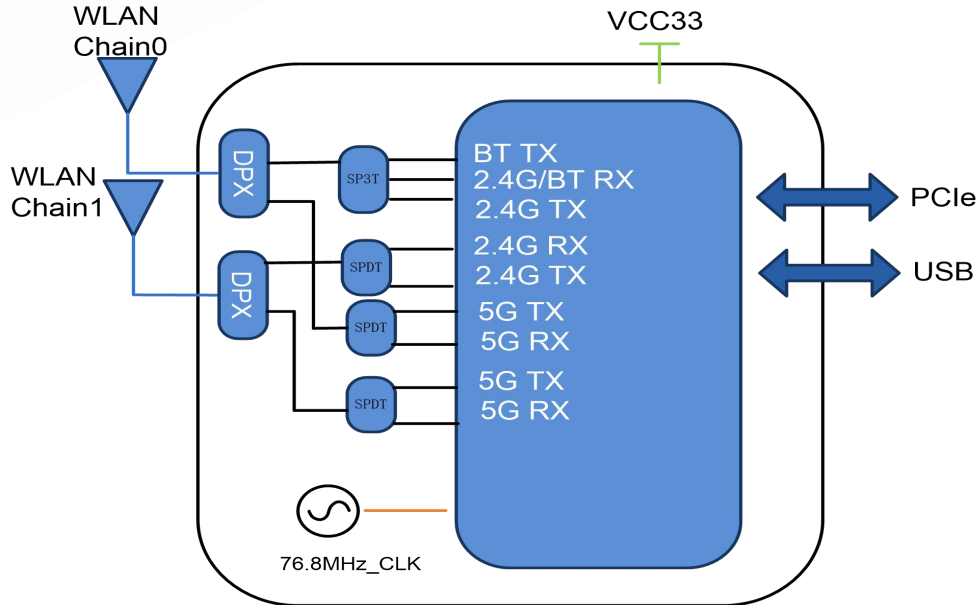
### WLAN Interface

- Low-power PCIe (with L1 substate) interface.

### Bluetooth Features

- Compliant with Bluetooth Milan.
- Split ACL support for A2DP true stereo.
- Dual Mode support: Simultaneous LE and BR/EDR.
- Flexible interface SlimbusPCM /I2S for Bluetooth audio.
- BT host digital interface: USB

## 3. Block Diagram



## 4. General Specification

### 4.1 2.4GHz RF Specification

Feature	Description	
WLAN Standard	IEEE 802.11 b/g/n/ac/ax Wi-Fi compliant	
Frequency Range	2.400 GHz ~ 2.4835 GHz (2.4 GHz ISM Band)	
Number of Channels	2.4GHz: Ch1 ~ Ch14	
Test Items	Typical Value	EVM
Output Power	802.11b /11Mbps : 17dBm ± 2 dB	EVM ≤ -9dB
	802.11g /54Mbps : 14dBm ± 2 dB	EVM ≤ -25dB
	802.11n HT20/MCS7 : 13dBm ± 2 dB	EVM ≤ -28dB
	802.11n HT40/MCS7 : 13dBm ± 2 dB	EVM ≤ -28dB
	802.11ax HE20/MCS11: 11dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE40/MCS11: 10dBm ± 2 dB	EVM ≤ -35dB
Spectrum Mask	Meet with IEEE standard	
Freq. Tolerance	± 20ppm	
Test Items	TYP Test Value	Standard Value
SISO Receive Sensitivity (11b,20MHz) @8% PER	- 1Mbps @ -94 dBm	≤-83 dBm
	- 11Mbps @ -85 dBm	≤-76 dBm
SISO Receive Sensitivity (11g,20MHz) @10% PER	- 6Mbps @ -90 dBm	≤-85 dBm
	- 54Mbps @ -71 dBm	≤-68 dBm
SISO Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0 @ -90 dBm	≤-85 dBm
	- MCS=7 @ -69 dBm	≤-67 dBm
SISO Receive Sensitivity (11n ,40MHz) @10% PER	- MCS=0 @ -87 dBm	≤-82 dBm
	- MCS=7 @ -66 dBm	≤-64 dBm
SISO Receive Sensitivity (11ac,20MHz) @10% PER	- MCS=0 @ -90 dBm	≤ -82 dBm
	- MCS=8 @ -64 dBm	≤ -60 dBm
SISO Receive Sensitivity (11ac ,40MHz) @10% PER	- MCS=0 @ -87 dBm	≤ -79 dBm
	- MCS=9 @ -59 dBm	≤ -55 dBm
SISO Receive Sensitivity (11ax,20MHz) @10% PER	- MCS=0 @ -90 dBm	≤-74 dBm
	- MCS=11 @ -60 dBm	≤-52 dBm
SISO Receive Sensitivity (11ax ,40MHz) @10% PER	- MCS=0 @ -87 dBm	≤-71 dBm
	- MCS=11 @ -57 dBm	≤-49 dBm
Maximum Input Level	802.11b : -10 dBm	

	802.11g/n : -20 dBm
Antenna Reference	Small antennas with 0~2 dBi peak gain

## 4.2 5GHz RF Specification

Conditions : VBAT=3.3V ; Temp:25°C

Feature	Description	
WLAN Standard	IEEE 802.11a/n/ac/ax, Wi-Fi compliant	
Frequency Range	5.1500 GHz ~ 5.850 GHz (5.0 GHz ISM Band)	
Number of Channels	full band supported	
Test Items	Typical Value	EVM
Output Power <sup>2</sup>	802.11a /54Mbps: 13 dBm ± 2 dB	EVM ≤ -25dB
	802.11n HT40/MCS7: 12dBm ± 2 dB	EVM ≤ -28dB
	802.11ac VHT80/MCS9: 10 dBm ± 2 dB	EVM ≤ -32dB
	802.11ax HE20/MCS11: 9 dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE40/MCS11: 9 dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE80/MCS11: 9 dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE160/MCS11: 8 dBm ± 2 dB	EVM ≤ -35dB
Test Items	Test Value	Standard Value
SISO Receive Sensitivity (11a,20MHz) @10% PER	- 6Mbps @ -90 dBm	≤-85
	- 54Mbps @ -71 dBm	≤-68
SISO Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0 @ -90 dBm	≤-85
	- MCS=7 @ -69 dBm	≤-67
SISO Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0 @ -87 dBm	≤-82
	- MCS=7 @ -66 dBm	≤-64
SISO Receive Sensitivity (11ac,20MHz)@10% PER	- MCS=0, NSS1 @ 90 dBm	≤-82
	- MCS=8, NSS1 @ -64 dBm	≤-60
SISO Receive Sensitivity (11ac,40MHz) @10% PER	- MCS=0, NSS1 @ -87 dBm	≤-79
	- MCS=9, NSS1 @ -59 dBm	≤-55
SISO Receive Sensitivity (11ac,80MHz) @10% PER	- MCS=0, NSS1 @ -84 dBm	≤-79
	- MCS=9, NSS1 @ -56 dBm	≤-54
SISO Receive Sensitivity (11ax,20MHz) @10% PER	- MCS=0 @ -90 dBm	≤-74
	- MCS=11 @ -58 dBm	≤-52
SISO Receive Sensitivity (11ax,40MHz) @10% PER	- MCS=0 @ -87 dBm	≤-71
	- MCS=11 @ -54 dBm	≤-49



SISO Receive Sensitivity (11ax,80MHz) @10% PER	- MCS=0 @ -84 dBm	≤-68
	- MCS=11 @ -48 dBm	≤-46
Maximum Input Level	802.11a/n: -30 dBm	
Antenna Reference	Small antennas with 0~2 dBi peak gain	

### 4.3 6GHz RF Specification

Feature	Description	
WLAN Standard	IEEE 802.11a/n/ac/ax, Wi-Fi compliant	
Frequency Range	5.925 GHz ~ 7.125 GHz	
Number of Channels	Full band supported	
Test Items	Typical Value	EVM
Output Power	802.11a /54Mbps: 12 dBm ± 2 dB	EVM ≤ -25dB
	802.11n HT40/MCS7: 10dBm ± 2 dB	EVM ≤ -28dB
	802.11ac VHT80/MCS9: 9 dBm ± 2 dB	EVM ≤ -32dB
	802.11ax HE20/MCS11: 8 dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE40/MCS11: 8 dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE80/MCS11: 7 dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE160/MCS11: 7 dBm ± 2 dB	EVM ≤ -35dB
Test Items	Test Value	Standard Value
SISO Receive Sensitivity (11a,20MHz) @10% PER	- 6Mbps @ -90 dBm	≤-85
	- 54Mbps @ -71 dBm	≤-68
SISO Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0 @ -90 dBm	≤-85
	- MCS=7 @ -69 dBm	≤-67
SISO Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0 @ -87 dBm	≤-82
	- MCS=7 @ -66 dBm	≤-64
SISO Receive Sensitivity (11ac,20MHz)@10% PER	- MCS=0, NSS1 @ 90 dBm	≤-82
	- MCS=8, NSS1 @ -64 dBm	≤-60
SISO Receive Sensitivity (11ac,40MHz) @10% PER	- MCS=0, NSS1 @ -87 dBm	≤-79
	- MCS=9, NSS1 @ -59 dBm	≤-55
SISO Receive Sensitivity (11ac,80MHz) @10% PER	- MCS=0, NSS1 @ -84 dBm	≤-79
	- MCS=9, NSS1 @ -56 dBm	≤-54
SISO Receive Sensitivity (11ax,20MHz) @10% PER	- MCS=0 @ -90 dBm	≤-74
	- MCS=11 @ -58 dBm	≤-52
SISO Receive Sensitivity (11ax,40MHz) @10% PER	- MCS=0 @ -87 dBm	≤-71
	- MCS=11 @ -54 dBm	≤-49
SISO Receive Sensitivity (11ax,80MHz) @10% PER	- MCS=0 @ -84 dBm	≤-68
	- MCS=11 @ -48 dBm	≤-46

Maximum Input Level	802.11a/n: -30 dBm
Antenna Reference	Small antennas with 0~2 dBi peak gain

## 4.2 Bluetooth Specification

Feature	Description		
<b>General Specification</b>			
Bluetooth Standard	Bluetooth V5.3		
Host Interface	USB		
Antenna Reference	Small antennas with 0~2 dBi peak gain		
Frequency Band	2402 MHz ~ 2480 MHz		
Number of Channels	79 channels		
Modulation	GFSK, $\pi/4$ -DQPSK, 8-DPSK		
<b>RF Specification</b>			
	<b>Min(dBm)</b>	<b>Typical(dBm)</b>	<b>Max(dBm)</b>
Output Power	2	9	15
Sensitivity @ BER=0.1% for GFSK (1Mbps)		-89	
Sensitivity @ BER=0.01% for $\pi/4$ -DQPSK (2Mbps)		-86	
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)		-85	
Maximum Input Level	GFSK (1Mbps):-20dBm		
	$\pi/4$ -DQPSK (2Mbps) :-20dBm		
	8DPSK (3Mbps) :-20dBm		

## 5. ID setting information

WI-FI

Vendor ID	-
Product ID	-

## 6. Pin Definition

### 6.1 Pin Outline

< TOP VIEW >

BOT		TOP	
Signal	PIN	Signal	PIN
3V3	74	GND	75
3V3	72	NC/TDI	73
NC/TDO	70	NC/TRST_N	71
NC/TCK	68	GND	69
NC/TMS	66	NC	67
NC/WL_TXEN_LAA	64	NC	65
NC/LAA_TXEN	62	GND	63
NC/WL_DBGUART_RX	60	NC	61
NC/WL_DBGUART_TX	58	NC	59
WL_RF_KILL	56	GND	57
BT_RF_KILL	54	PCIE_WAKE	55
PCIE_RST	52	CLKREQ	53
SUSCLK	50	GND	51
NC/LTE_COEX_RXD	48	PCIE_CLKN	49
NC/LTE_COEX_TXD	46	PCIE_CLKP	47
NC	44	GND	45
NC	42	PCIE_TXN	43
NC	40	PCIE_TXP	41
NC/SRST_N	38	GND	39
NC	36	PCIE_RXN	37
NC	34	PCIE_RXP	35
NC	32	GND	33
KEY-E	24-34	KEY-E	25-31
NC	22	NC	23
NC/BT_WAKE_HOST	20	NC	21
GND	18	NC	19
NC/BT_LED	16	NC	17
BT_I2S_SD1	14	NC	15
BT_I2S_SDO	12	NC	13
BT_I2S_WS	10	NC	11
BT_I2S_SCK	8	NC	9
NC/WL_LED	6	GND	7
3V3	4	USB-	5
3V3	2	USB+	3
		GND	1



## 6.2 Pin Definition details

NO	Name	Type	Description	Voltage
1	GND	-	Ground connections	
3	USB_D+	I/O	USB differential line for BT	
5	USB_D-	I/O	USB differential line for BT	
7	GND	-	Ground connections	
9	NC	-	Floating (NC)	
11	NC		Floating (NC)	
13	NC		Floating (NC)	
15	NC		Floating (NC)	
17	NC	-	Floating (NC)	
19	NC	-	Floating (NC)	
21	NC	-	Floating (NC)	
23	NC	-	Floating (NC)	
33	GND	-	Ground connections	
35	PCIE_RXP	I	PCIe RX differential signals	
37	PCIE_RXN	I		
39	GND	-	Ground connections	
41	PCIE_TXP	O	PCIe TX differential signals	
43	PCIE_TXN	O		
45	GND	-	Ground connections	
47	PCIE_CLKP	I	PCIe clock differential input signal	
49	PCIE_CLKN	I		
51	GND		Ground connections	
53	CLKREQ	O	PCIe reference clock request signal, open drain, active low.	3.3V
55	PCIE_WAKE	O	PCIe wake up host, open drain, active low.	3.3V
57	GND	-	Ground connections	
59	NC	-	Floating (NC)	

61	NC	-	Floating (NC)	
63	GND	-	Ground connections	
65	NC	-	Floating (NC)	
67	NC	-	Floating (NC)	
69	GND	-	Ground connections	
71	NC/TRST_N	-	Floating (NC)	
73	NC/TDI	-	Floating (NC)	
75	GND	-	Ground connections	

**Bottom side**

<b>NO</b>	<b>Name</b>	<b>Type</b>	<b>Description</b>	<b>Voltage</b>
2	3_3V	P	Power supply	3.3V
4	3_3V	P	Power supply	3.3V
6	NC/WL_LED	O	No function,Floating (NC)	3.3V
8	BT_I2S_SCK	-	Or PCM CLK,If not used can Floating	1.8V
10	BT_I2S_WS	-	Or PCM SYNC,If not used can Floating	1.8V
12	BT_I2S_SDO	-	Or PCM OUT,If not used can Floating Reserve 10k pull up.	1.8V
14	BT_I2S_SDI	-	Or PCM IN,If not used can Floating	1.8V
16	NC/BT_LED	O	No function,Floating (NC)	3.3V
18	GND	-	Ground connections	
20	NC/BT_WAKE_HOST	-	No function,Floating (NC)	3.3V
22	NC	-	Floating (NC)	
32	NC		Floating (NC)	
34	NC	-	Floating (NC)	
36	NC	-	Floating (NC)	
38	NC/SRST_N	-	No function,Floating (NC)	
40	NC	-	Floating (NC)	
42	NC	-	Floating (NC)	
44	NC	-	Floating (NC)	
46	NC/LTE_COEX_TXD	O	No function,Floating (NC). Reserve for LTE coexistence signal	1.8V
48	NC/LTE_COEX_RXD	I	No function,Floating (NC).Reserve for LTE	1.8V

			coexistence signal	
50	NC/SUSCLK	I	No function,Floating (NC),External 32.768K clock input,when NC can use internal 32K.	1.8V
52	PCIE__RST	I	PCIe reset signal, active low	3.3V
54	BT_RF_KILL	I	Bluetooth disable signal, pull low to disable BT function, default high.	3.3V
56	WL_RF_KILL	I	WLAN disable signal, pull low to disable WLAN function, External pull high needed.	3.3V
58	NC/WL_DBGUART_TX	-	Floating (NC)	1.8V
60	NC/WL_DBGUART_RX	-	Floating (NC)	1.8V
62	NC/LAA_TXEN	-	Floating (NC)	1.8V
64	NC/WL_TXEN_LAA	-	Floating (NC)	1.8V
66	NC/TMS	-	Floating (NC)	1.8V
68	NC/TCK	-	Floating (NC)	1.8V
70	NC/TDO	-	Floating (NC)	1.8V
72	3_3V	P	Power supply	3.3V
74	3_3V	P	Power supply	3.3V

P:POWER I:INPUT O:OUTPUT

## 7. Electrical Specifications

### 7.1 Power Supply DC Characteristics

	MIN	TYP	MAX	Unit
Operating Temperature	-20	25	70	deg.C
VDD33	3.0	3.3	3.6	V

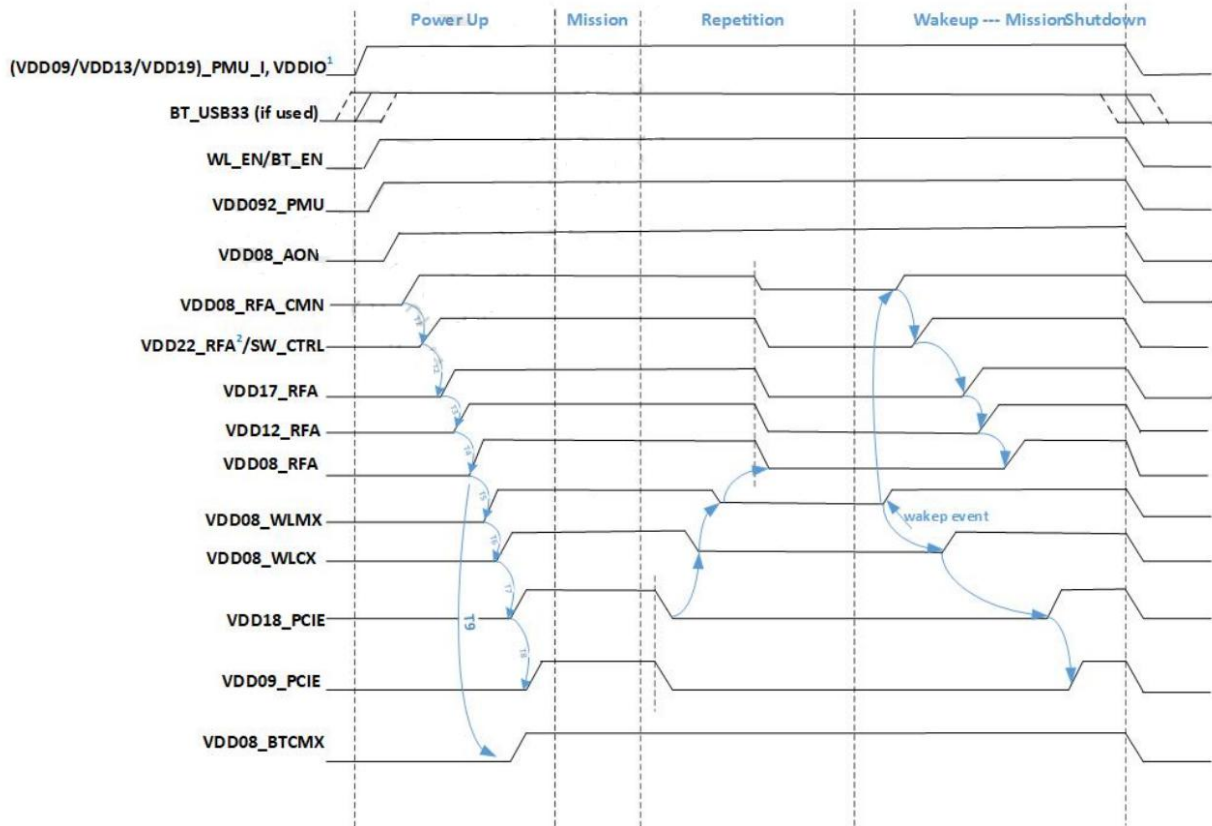
### 7.2 Power Consumption

Power Consumption	3.3V(Unit:W)	
	TX (2.4G HE40 6M)	2.85
	RX (2.4G HE40 6M)	0.8

	TX(2.4G HE40 MCS11)	2.54
	RX(2.4G HE40 MCS11)	0.8
	TX(5G HE160 MCS11)	2.97
	RX(5G HE160 MCS11)	0.8
	TX(6G HE160 MCS11)	3.43
	RX(6G HE160 MCS11)	0.9
	TX DBS2G+5G	4.97
	RX DBS2G+5G	0.8
	TX DBS2G+6G	5.23
	RX DBS2G+6G	0.8
	BT TX	0.44
	BT RX	0.32

### 7.3 Interface Circuit time series

#### 7.3.1 PCIe Bus during Power On Sequence



1. All input supplies must be ON and available before WLAN/BT\_EN is asserted. There is no requirement on the order of input supply.
2. VDD22\_RFA is used as internal PA supply and follows SW\_CTRL. For design with external PA only, VDD22



pins need to be connected to the 1.9V input. Refer to reference schematic for details.




**Power sequence timing parameters**

Symbol	Description	Timing	Unit
T1	The delay time from RFACMN LDO to SW_CTRL = H	1.35	ms
T2	The delay time from SW_CTRL = H to enable RFA_VDD17	2	ms
T3	The delay time from turn on RFA_VDD17 to turn on RFA_VDD12	80	µs
T4	The delay time from turn on RFA_VDD12 to turn on RFA_VDD08	80	µs
T5	The delay time from turn on RFA_VDD08 to turn on both WL_MX	3.43	ms
T6	The delay time from turn on WL_MX to turn on WL_CX	1.205	ms
T7	The delay time from turn on WL_CX to turn on PCIE_VDD_18	1.205	ms
T8	The delay time from turn on PCIE_VDD_18 to turn on PCIE_VDD_95	1.13	ms
T9	The delay time from turn on RFA_VDD08 to turn on BT_CMX	4.33 <sup>1</sup>	ms

<sup>1</sup> Timing is 4.33 ms if WLAN is enabled and TCXO is used; timing is 4.98 ms if WLAN is enabled and XO is used; timing is 3.99 ms if only Bluetooth enabled and TCXO is used; timing is 4.64 ms if only Bluetooth enabled and XO is used.

## 8. Size reference

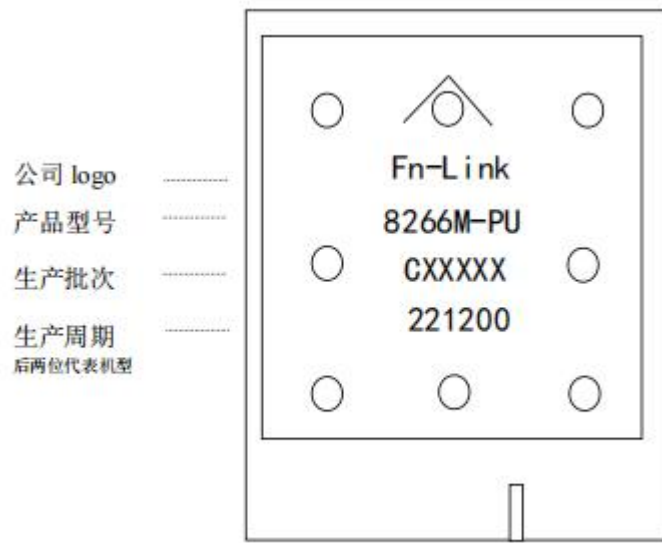
### 8.1 Module Picture

<p>L x W : 22 x 30 (+0.3/-0.1) mm</p> 	
<p>H: 2.2 (±0.2) mm</p>	
<p><b>Weight</b></p>	<p>2.8g</p>

### 8.2 Marking Description

< TOP VIEW >

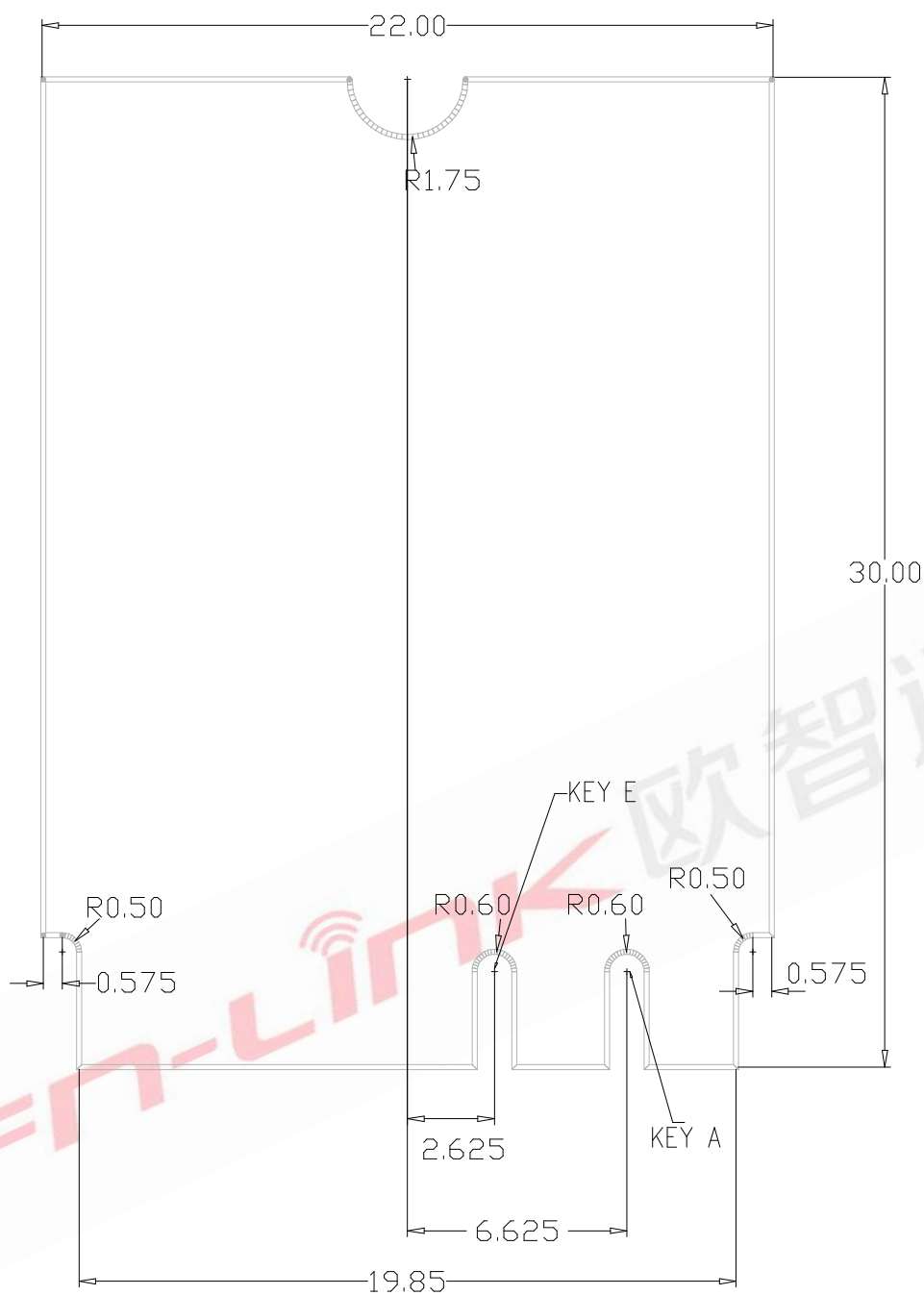




### 8.3 Physical Dimensions

<TOP View>

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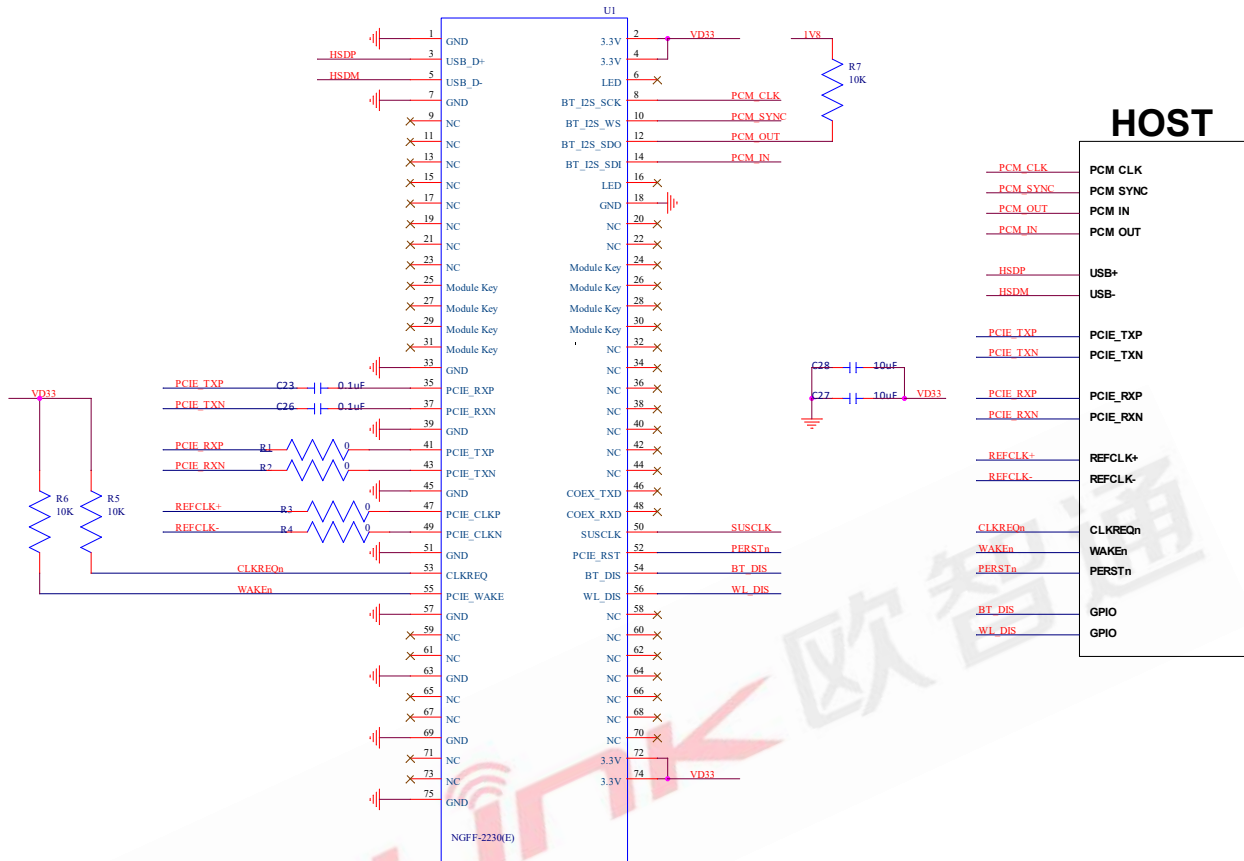
module is key-E type

## 9. The Key Material List

Item	Part Name	Description	Manufacturer
1	PCB	8266M-PU Green,HDI 6L,FR4,AU,22X30X0.8mm	Sunlord, GDKX, Truly PCB,Brain-power
2	Inductor	2012 0.47uH,±20%,Isat=4.5A Irms=4.0A	Sunlord, Ceaiya, Cenker,Chilisin,Murata,INPAQ
3	Diplexer	Diplexer,1608	Glead, Walsin, ACX, Murata, MAG.LAYERS,ftgroup,TDK
4	Crystal	1210,76.8MHZ, ±10PPM,10PF	ECEC, TKD, Hosonic, JWT, TXC
5	Chipset	QCA-2066-5-NSP288-MT-02-1,Tri-band 2x2 802.11ax+BT5.3	Qualcomm
6	Shielding	8266M-PU,Shielding cover,21.45X20.57X1.4mm,T=0.2mm	Suntech, JLitong,卓益
7	IC	PMCA6850 (001-0-02), WLNSP49D, P MIC FOR WCN6850, 2SMPS+7LDO	Qualcomm
8	SWITCH	3T Switch, MXD8730L SPDT Switch,MXD8723E	卓胜微
9	LNA	MXD7516,LNA,WIFI6 5-7.2GHZ,802.11N/AC/AX,1.6-3.6V,15.5DB	卓胜微

# 10. Reference Design

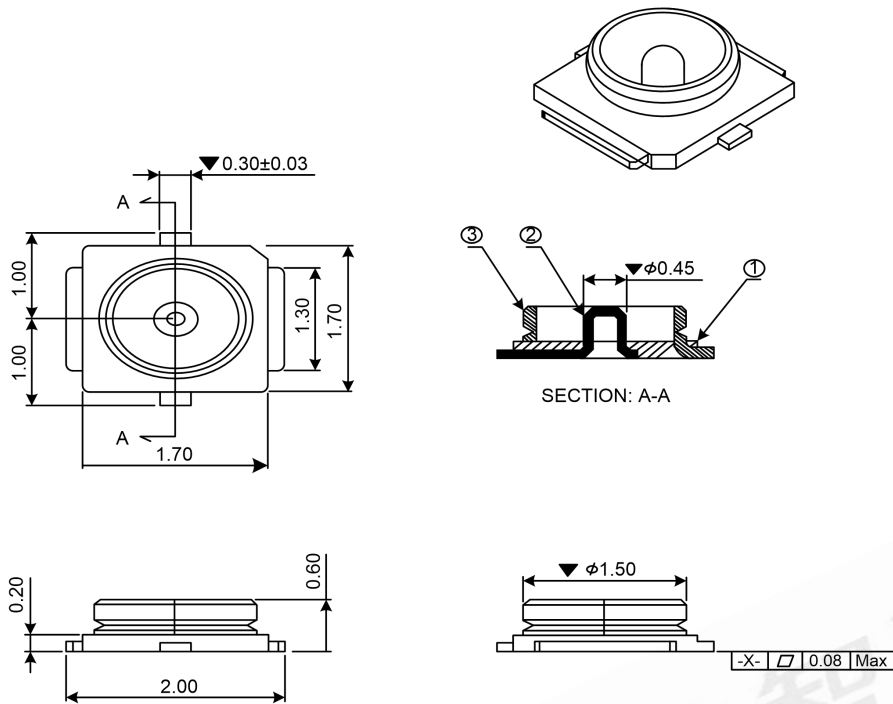
## 10.1 Reference design



Note:

1. PCIe differential keep 100 ohm trace.
2. USB differential keep 90 ohm trace.

## 10.2 Connector Specification



## 11. Recommended Reflow Profile

No need to do SMT reflow process.

## 12. RoHS compliance

All hardware components are fully compliant with EU RoHS directive

## 13. Package

### 13.1 Tray

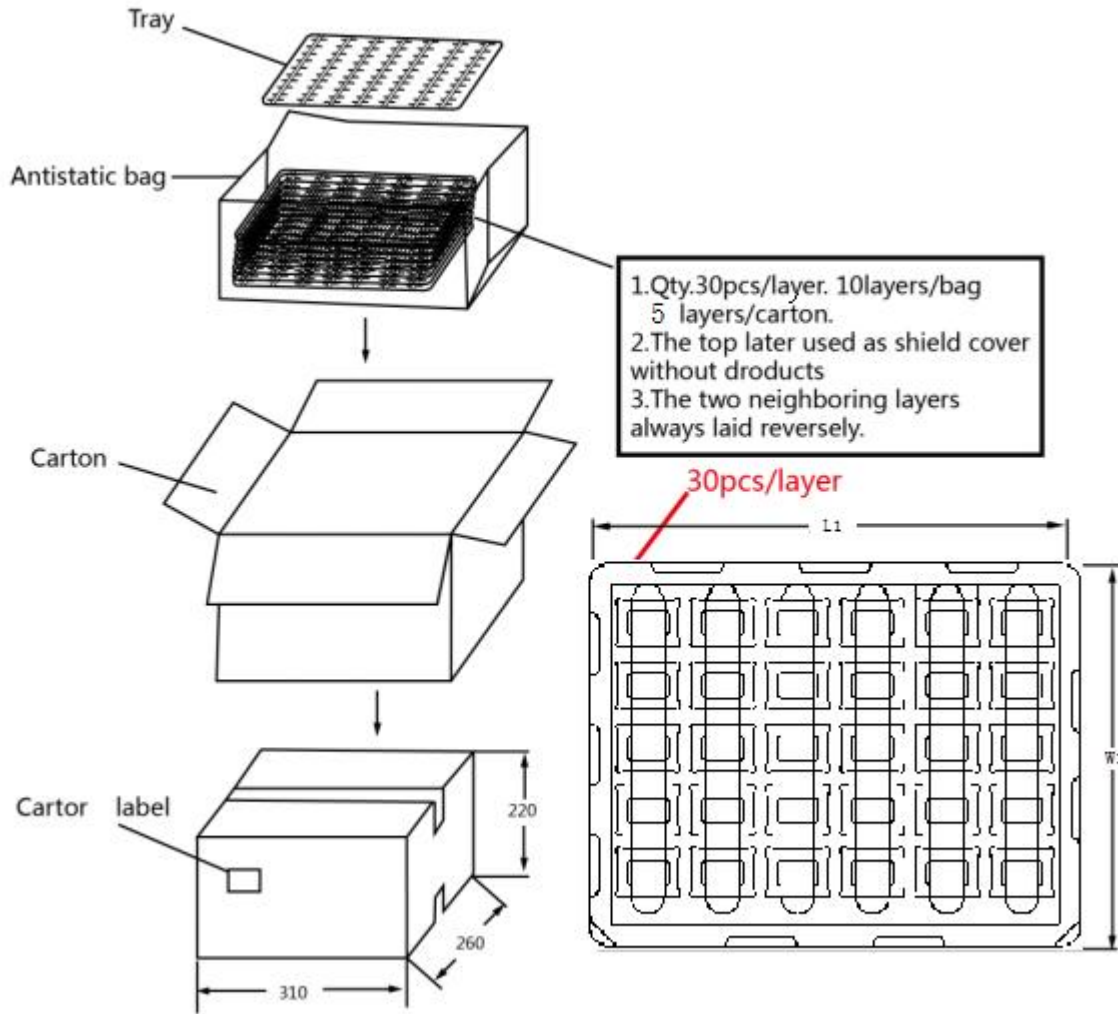
Layer size: L250.0\*W190.0 mm

Layer material: PVC

Carton size: L310.0\*W260.0\*H220.0 mm

Carton material: A=A

Total=1500pcs



## 14. Moisture sensitivity

The Modules is a Moisture Sensitive Device level 3, in according with standard IPC/JEDEC J-STD-020, take care

all the relatives requirements for using this kind of components.

Moreover, the customer has to take care of the following conditions:

- a) Calculated shelf life in sealed bag: 12 months at <math><40^{\circ}\text{C}</math> and <math><90\%</math> relative humidity (RH)
- b) Environmental condition during the production: <math>30^{\circ}\text{C}</math> / 60% RH according to IPC/JEDEC J-STD-033A paragraph 5
- c) The maximum time between the opening of the sealed bag and the reflow process must be 168 hours if

condition

- d) “IPC/JEDEC J-STD-033A paragraph 5.2” is respected
- e) Baking is required if conditions b) or c) are not respected
- f) Baking is required if the humidity indicator inside the bag indicates 10% RH or more

FN-LINK 欧智通